L	Hits	Search Text	DB	Time stamp
Number				
1	0	(light-emitting-diode light-emitter) and	USPAT;	2004/09/25
		wafer-bond\$3 and solder	US-PGPUB;	10:27
		,	EPO; JPO;	
			IBM_TDB	1
2	0	, (== 9.00 0= 0.0=0.0 0= = = - 9.00 0= 0= ,	USPAT;	2004/09/25
		wafer-bond\$3 with (intermetallic metal	US-PGPUB;	10:29
		metallic)	EPO; JPO;	İ
			IBM_TDB	!
3	3	(light-emitting-diode light-emitter	USPAT;	2004/09/25
		diode) and wafer-bond\$3 with	US-PGPUB;	11:18
		(intermetallic metal metallic)	EPO; JPO;	
			IBM_TDB	
4	1	("5508718").PN.	USPAT;	2004/09/25
			US-PGPUB;	10:38
1			EPO; JPO;	
ŀ			IBM_TDB	1
5	1	("5008718").PN.	USPAT;	2004/09/25
			US-PGPUB;	10:43
			EPO; JPO;	
			IBM_TDB	
6	15	chen-shi-ming.in.	USPAT;	2004/09/25
			US-PGPUB;	10:43
			EPO; JPO;	
			IBM_TDB	
7	25		USPAT;	2004/09/25 .
		diode) and (metal\$3 near3 eutectic near3	US-PGPUB;	11:20
		bond\$3) and transparen\$	EPO; JPO;	
		·	IBM_TDB	